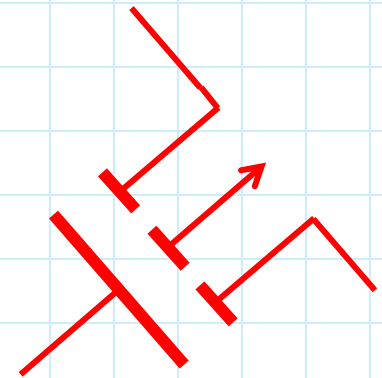


# Unit 2: THE MOSFET transistor



# Objectives

At the end of this chapter, the student should:

- Know the importance of MOSFET transistors in the development of computers, knowing their characteristics and their relationships with the success of the digital world.
- Know the operating principles of MOSFET transistors, their characteristic curves and operating regions.
- Solve simple DC circuits with one or more transistors.
- Understand MOSFET operation inside basic circuits and digital switching systems.
- Known protection techniques for MOSFETs inputs

# Unit 2: Contents

## 2.1 Introduction

## 2.2 Basic principles of operation

- Operating regions
- Biasing

## 2.3 The MOSFET in switching mode

## 2.4 NMOS logic gates

## 2.5 The CMOS inverter

## 2.6 Protecting circuits for MOSFET transistors

## 2.7 Summary

# Bibliography

## *THEORY:*

- A.R.Hambley, “Electronics” (2<sup>a</sup> Ed.)”, Prentice Hall, 2002.
- M.H.Rashid, “Microelectronic circuits. Analysis and design”, Thomson, 2002.
- N. R. Malik, “Electronic circuits: analysis, simulation and design”, Prentice Hall, 2000.
- R. Boylestad, L. Nashelsky, “Electronics, circuit theory”, Pearson, 2009.
- A.P. Malvino, D.J. Bates, “Electronic principles”, Mc Graw Hill, 2007.

## *PROBLEMS:*

- G. Benet, J. V. Benlloch, V. Busquets, D. Gil, P. Pérez: “Ejercicios resueltos de Tecnología de Computadores”, 2006.916

# 2.1 Introduction

FET = *Field Effect Transistor*

Current controlled by an electric field

Unipolar device

JFET (Junction FET), Shockley, 1952

MOSFET (Metal-Oxide-Semiconductor FET)

Kahn y Atalla, 1960

{ Deplexion  
Enhancement

{ N Channel (NMOS Transistor)  
P Channel (PMOS Transistor)

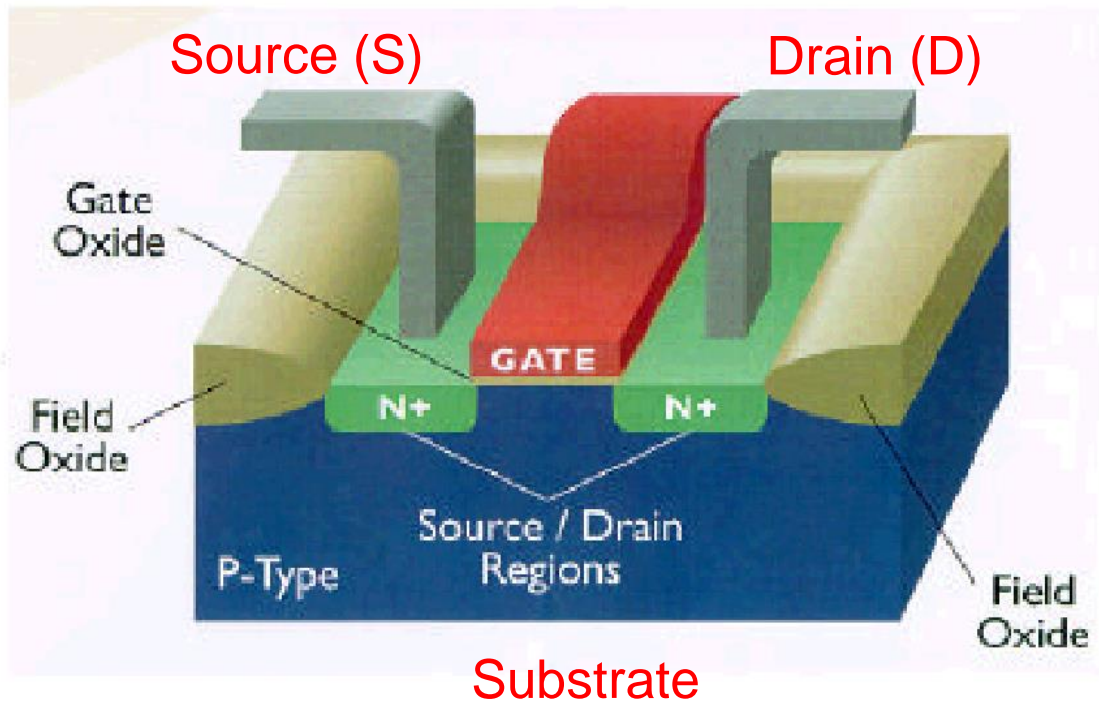
# 2.1 Introduction(2)

- Some advantages:
  - High integration density=> VLSI
  - Versatility: R, C, switch,
  - Low power
  - High input impedance
- Some drawbacks:
  - Slower than BJT
  - Less linearity

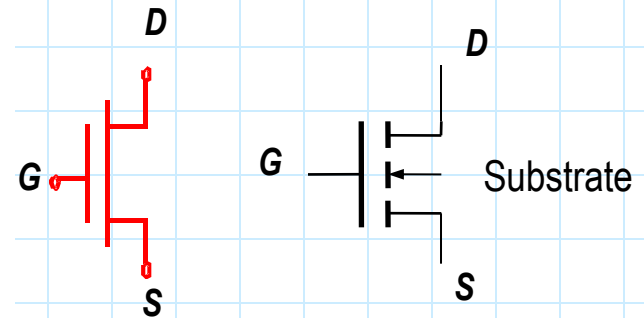
# 2.2 Basic principles of operation

## Internal structure:

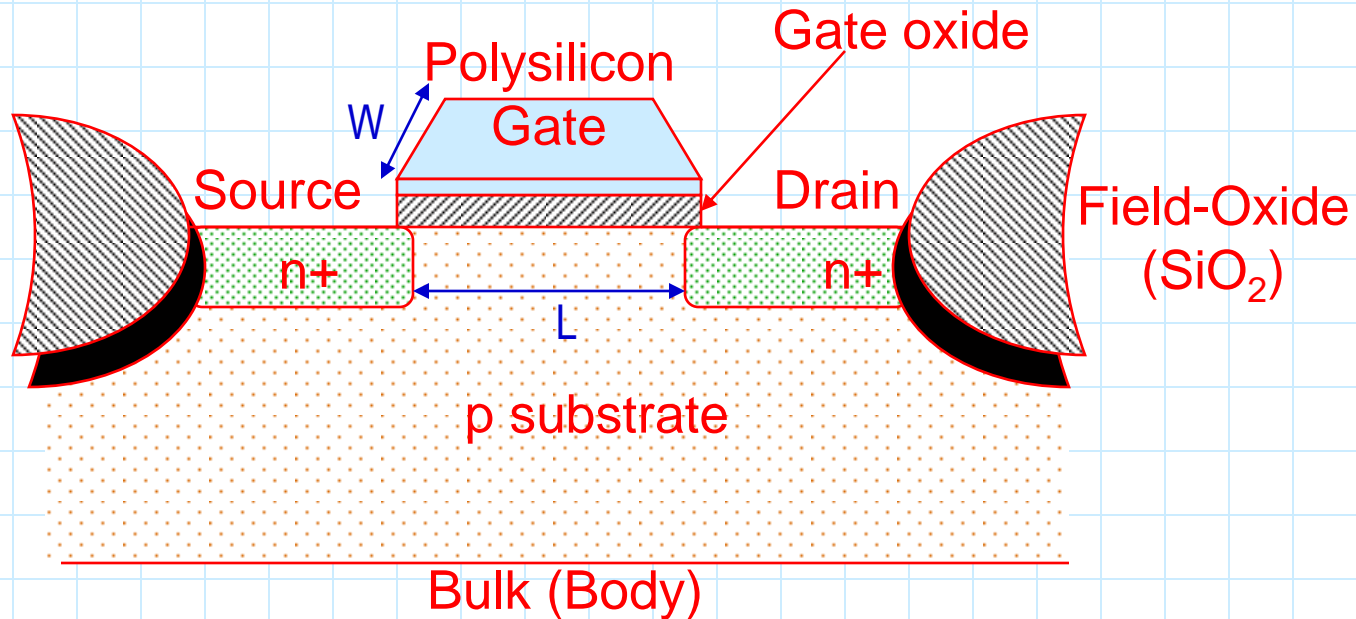
**N-channel Enhancement MOSFET (NMOS transistor):**



## Symbols



# NMOS Transistor: cross section



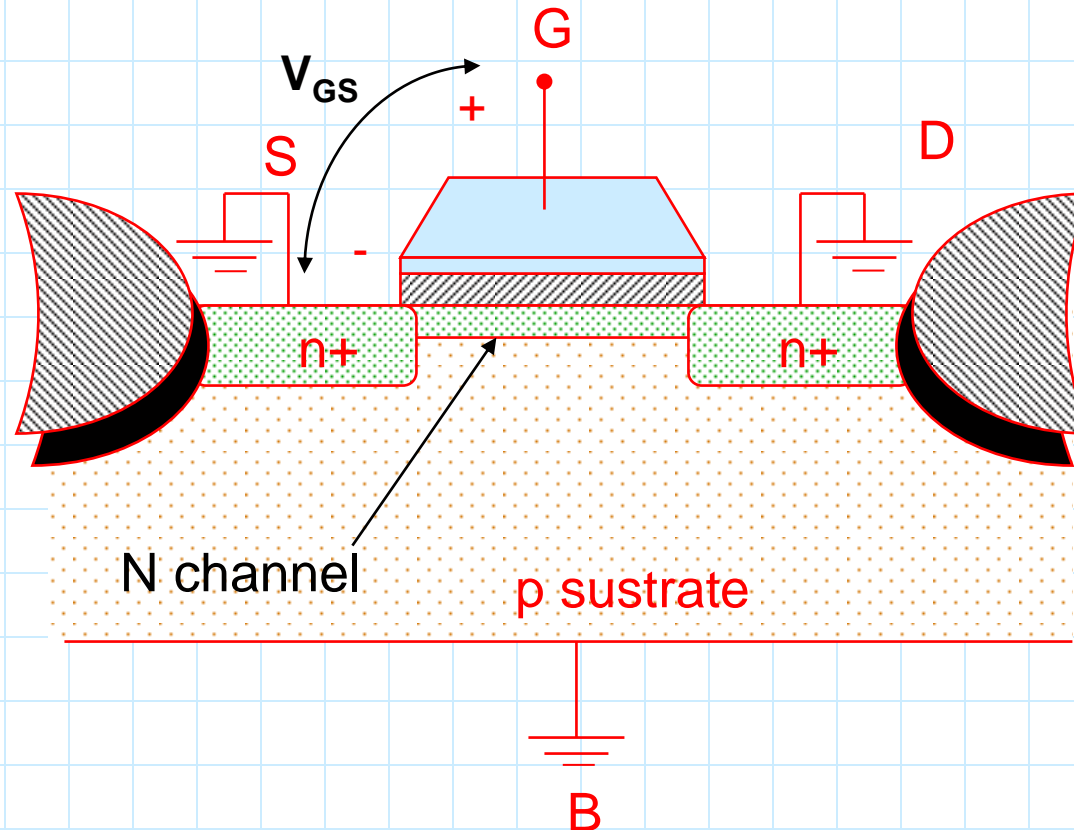
Constants:

$K$  (mA/V<sup>2</sup>)  
 $V_T$  (V)

*Pspice:*  $K = (W/L) K_p / 2$   
*Pspice:*  $V_T = v_{to}$



# Operating regions: channel formation

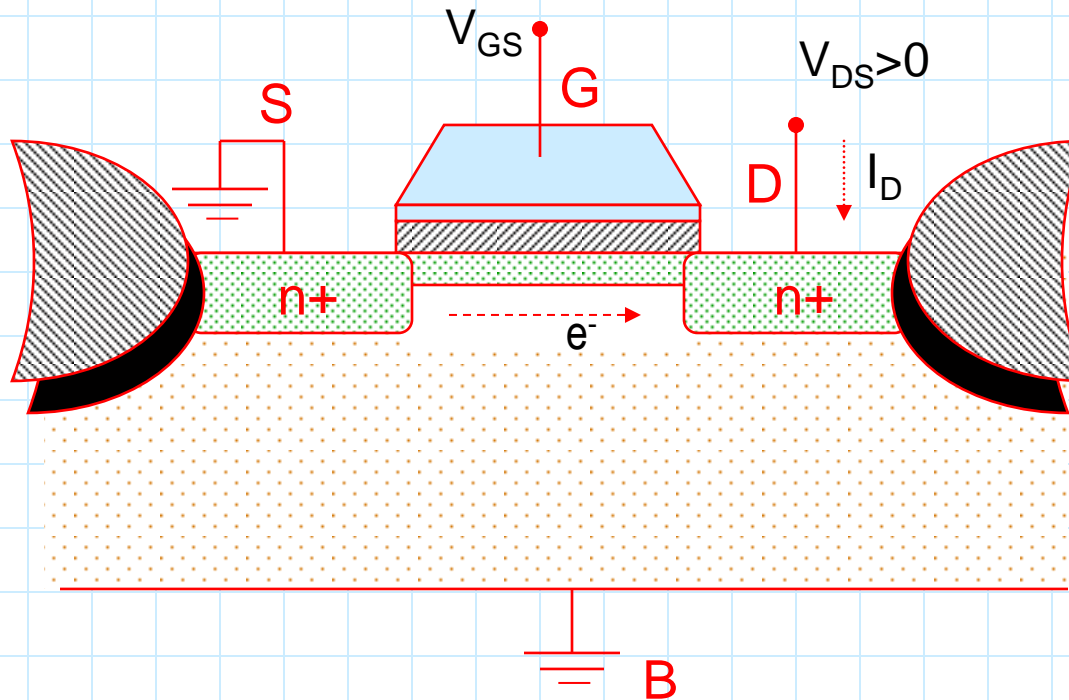


## Channel formation:

$V_{GS} > V_T$  : a N-type channel is formed between S and D  
 $V_{GS} \leq V_T$  : no channel is formed  $\rightarrow$  CUT-OFF

# Operating regions : ohmic region

Assuming  $V_{GS} > V_T$ :



Conducting condition:

$$V_{DS} > 0 \rightarrow I_{DS} > 0$$

# Working principles: linear region (2)

Condition:  $V_{DS} \leq V_{GS} - V_T$

V/I function:  $I_D = K [2(V_{GS} - V_T)V_{DS} - V_{DS}^2]$

For small  $V_{DS}$ :

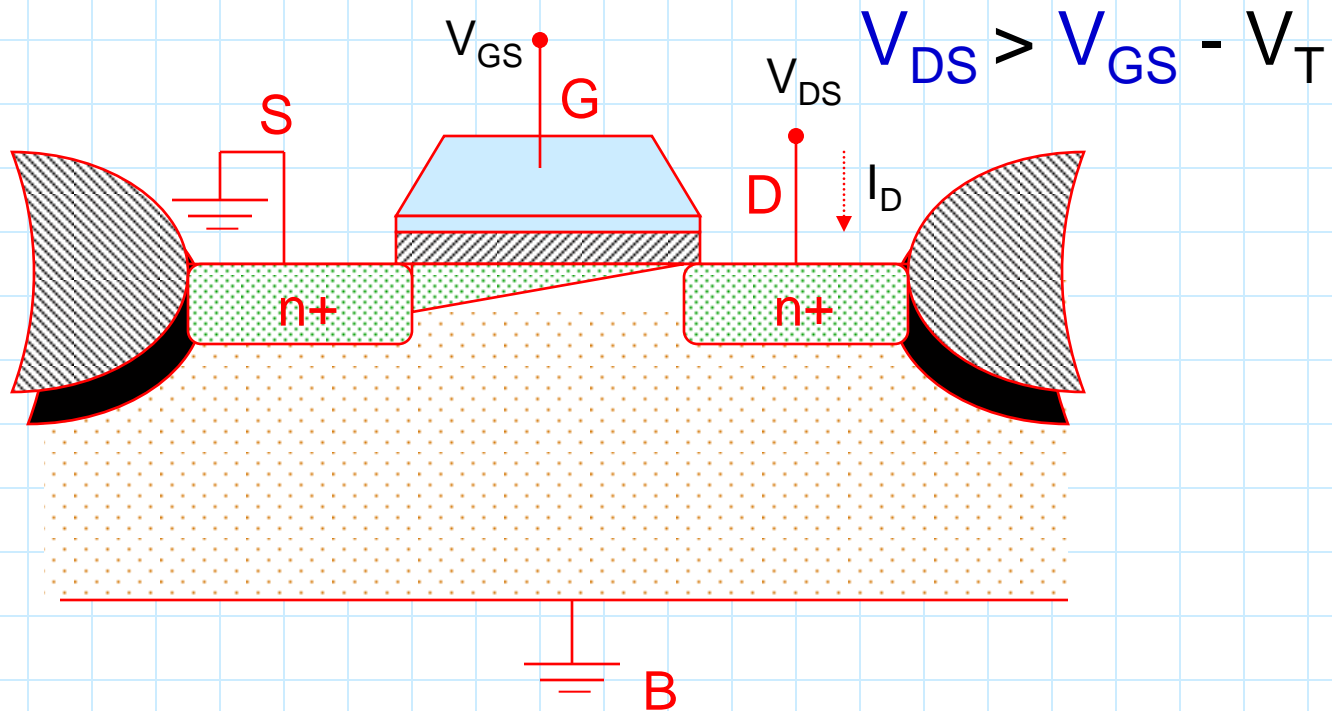
$$I_D \approx K [2 (V_{GS} - V_T) V_{DS}]$$

$$R_{DS(on)} = R_{ON} \approx \frac{1}{2 \cdot K (V_{GS} - V_T)}$$

The MOSFET resistance decreases when  $K$  and  $V_{GS}$  increase

# Operating regions: saturation region

Assuming  $V_{GS} > V_T$



The channel is pinched-off (small channel near D), and the current remains constant

# Operating regions: saturation region(2)

Condition:  $V_{DS} > V_{GS} - V_T$

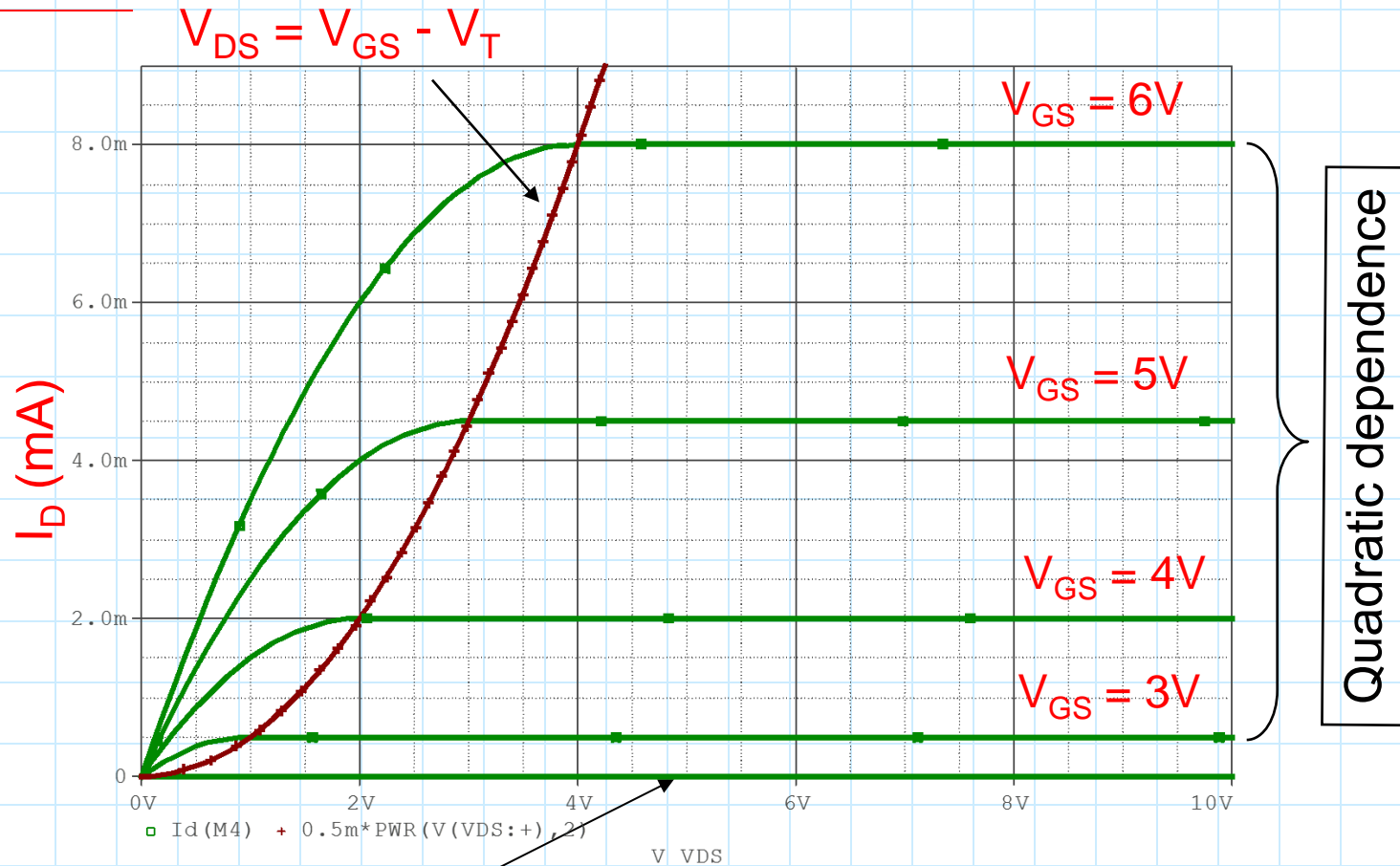
V/I function:  $I_{DS} = K (V_{GS} - V_T)^2$  (Saturation parable)

The channel is *pinched-off* →

For a fixed  $V_{GS}$ , the current  $I_{DS} \approx \text{constant}$ , and indep. of  $V_{DS}$

The Mosfet is equivalent to a current source ( $I_{DS}$ ) controlled by voltage ( $V_{GS}$ )

# I-V curves of the NMOS

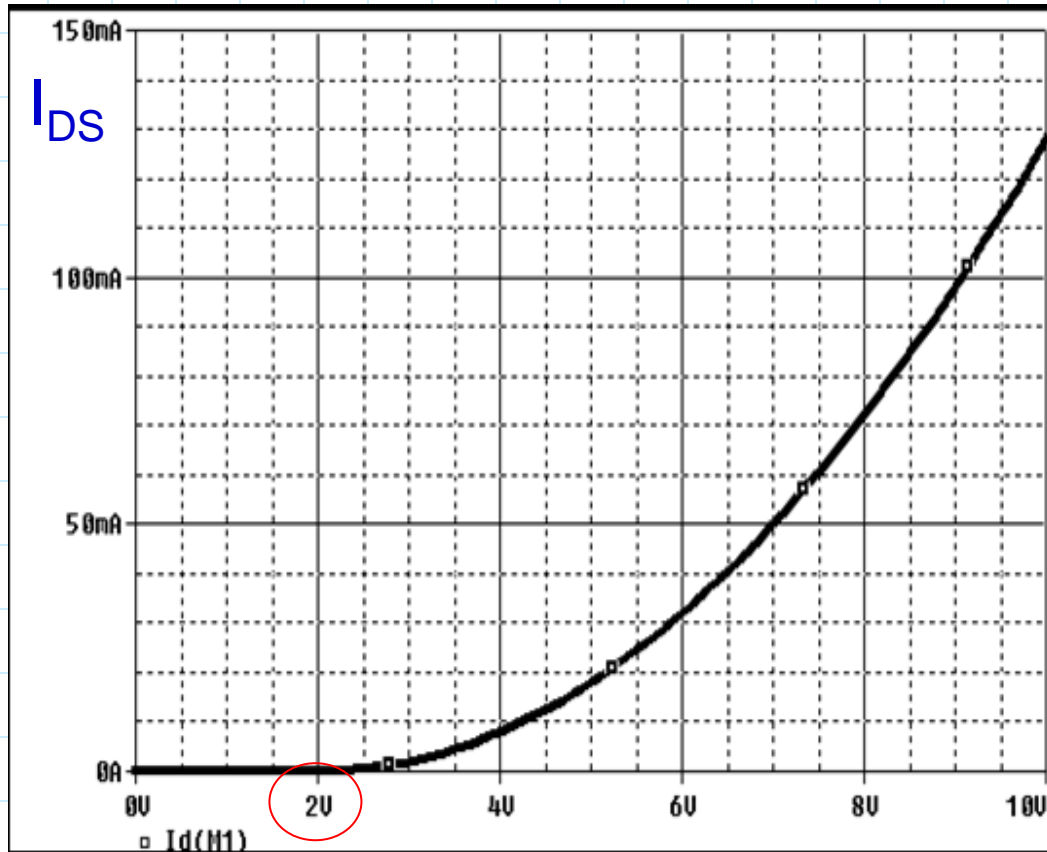


Cut-off:  $V_{GS} \leq 2V$

$V_{DS}$  (V)

Example: NMOS Transistor:  $V_T = 2V$      $K = 0.5mA/V^2$

# $I_{DS}$ versus $V_{GS}$ in saturation region



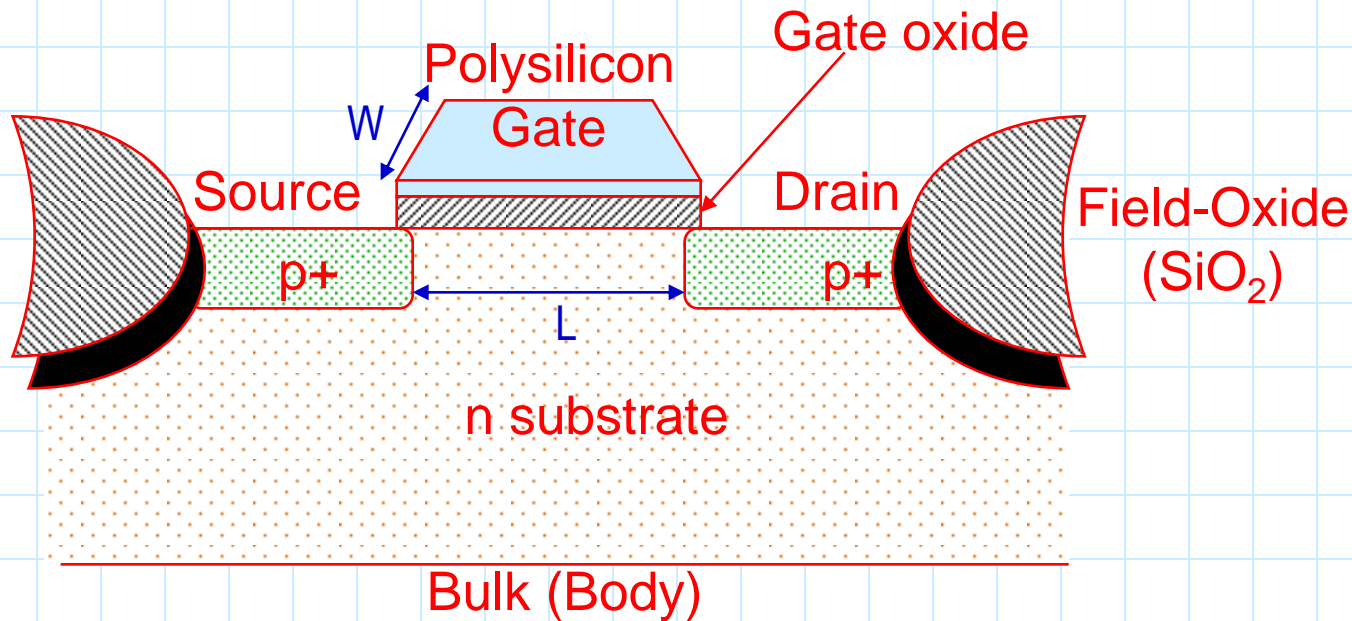
Saturation parable:

$$I_{DS} = K (V_{GS} - V_T)^2$$

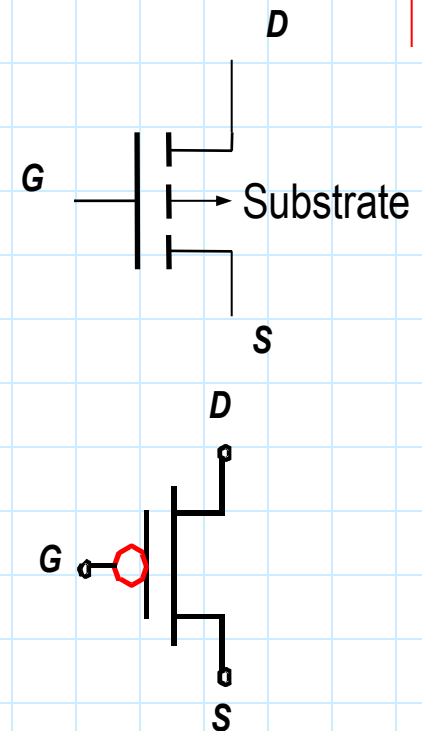
$$V_T = 2V$$

$$V_{GS} \leq V_T \rightarrow I_D = 0$$

# PMOS Transistor: cross section

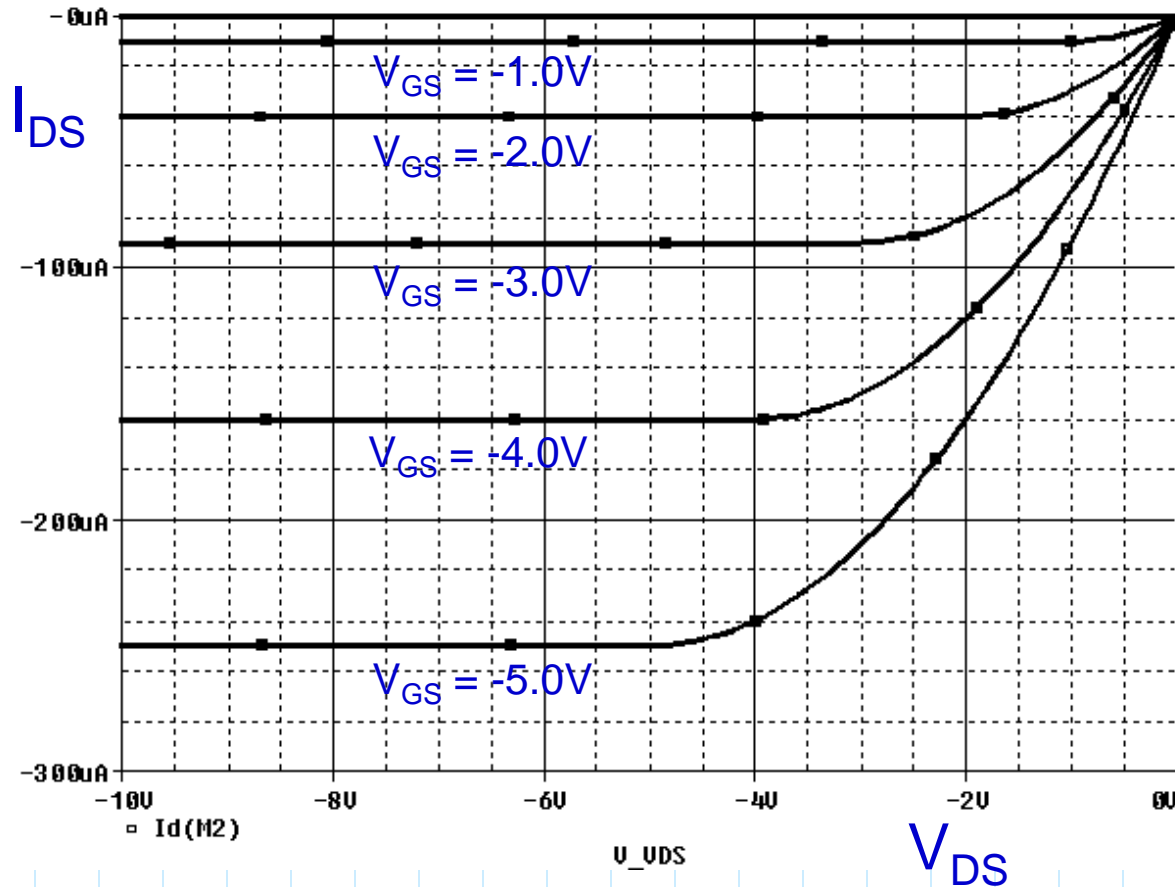


Symbols





# PMOS. Characteristic curves



All variables are negatives!

$$V_{GS} < 0, V_{DS} < 0, \\ I_{DS} < 0 \rightarrow I_{SD} > 0$$

Conduction:  $V_{GS} < -V_T$

# The PMOS transistor: summary

- Cut-off:  $V_{GS} \geq -V_T$

- Saturation:

$$V_{DS} < V_{GS} + V_T$$

$$I_{SD} = K (V_{GS} + V_T)^2$$

- Ohmic:

$$R_{ON} \approx \left| \frac{1}{2 \cdot K (V_{GS} + V_T)} \right|$$

(considering  $K$  and  $V_T$  as absolute values,  $V_{GS} < 0$ ,  $V_{DS} < 0$ )

- Less use than N-channel MOSFETS, as holes mobility is smaller than electrons mobility:
  - ◆ Slower than the NMOS
  - ◆ They need more  $W/L \rightarrow$  bigger than NMOS (more space occupied)

# MOSFET: Summary of some formulas

NMOS		PMOS
$V_{GS} > V_T$	CONDUCTS	$V_{GS} < -V_T$
$V_{DS} > V_{GS} - V_T$	SATURATION condition	$V_{DS} < V_{GS} + V_T$
$I_{DS} = K (V_{GS} - V_T)^2$	SATURATION	$I_{SD} = K (V_{GS} + V_T)^2$
$I_{DS} = K [2(V_{GS} - V_T)V_{DS} - V_{DS}^2]$  $R_{ON} \approx \frac{1}{2 \cdot K(V_{GS} - V_T)}$	OHMIC or LINEAR	$I_{SD} = K [2(V_{GS} + V_T)V_{DS} - V_{DS}^2]$  $R_{ON} \approx \left  \frac{1}{2 \cdot K(V_{GS} + V_T)} \right $

(Taking the absolute value of  $V_T$  and  $K$  in all formulas)

# Summary NMOS regions

NMOS	Equation	Check
CUT-OFF	$I_{DS} = 0$	$V_{GS} < V_T$
SATURATION	$I_{DS} = K (V_{GS} - V_T)^2$	$V_{DS} > V_{GS} - V_T$
OHMIC or LINEAR	$I_{DS} = K [2(V_{GS} - V_T)V_{DS} - V_{DS}^2]$ $R_{ON} \approx \frac{1}{2 \cdot K(V_{GS} - V_T)}$	$V_{DS} < V_{GS} - V_T$

(Taking the absolute value of  $V_T$  and  $K$  in all formulas)

# Equivalences and differences between Mosfet-BJTs

## Terminals

MOSFET	BJT
DRAIN	COLLECTOR
SOURCE	EMITTER
GATE	BASE

BJT:  $I_B > 0$  for conducting

Mosfet:  $I_G = 0$  always!

## Working regions

MOSFET	BJT
CUT-OFF REGION	CUT-OFF REGION
SATURATION REGION	ACTIVE REGION
OHMIC \ LINEAR REGIN	SATURATION REGION

Mosfet's Saturation : maximum  $I_{DS}$  for a given  $V_{GS}$

BJT's saturation: maximum  $I_C$  for a given biass circuit

# Enhancement MOSFET Biassing (1)

Equations to analyze the Mosfets biassing circuits

1.- Input loop: **G-S** → loop equation with  $V_{GS}$

2.- **Assuming** saturation → saturation equation

$$\text{NMOS: } I_{DS} = K (V_{GS} - V_T)^2 \quad \text{PMOS: } I_{SD} = K (V_{GS} + V_T)^2$$

*(With  $V_{GS}$ , checkout if MOSFET is conducting)*

3.- Output loop **D-S** → loop equation with  $V_{DS}$

4.- **Checkout** of saturation

$$\text{NMOS: } V_{DS} > V_{GS} - V_T$$

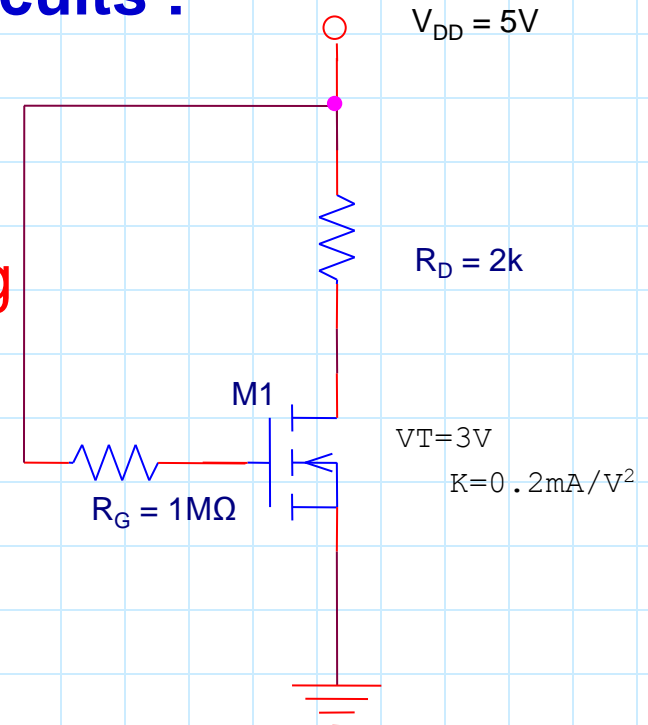
$$\text{PMOS: } V_{DS} < V_{GS} + V_T$$

*(If not satisfied, return to step 2, using the equation of the linear region, and redo the calculations)*

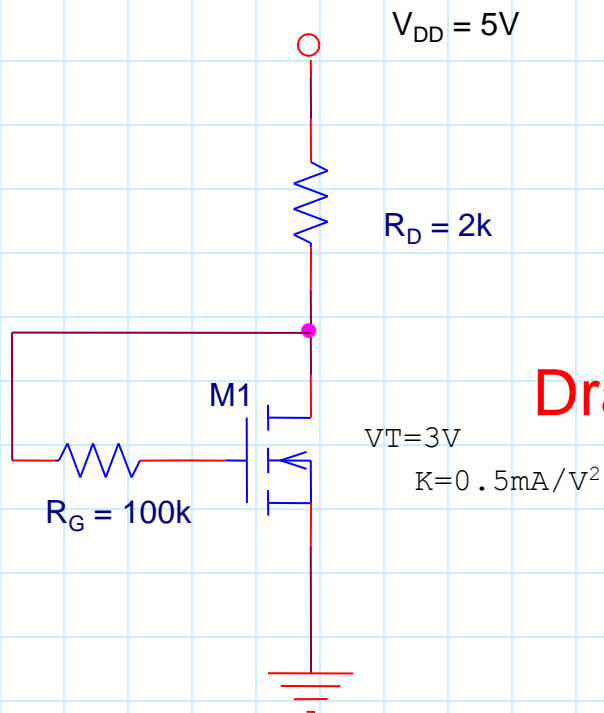
# Enhancement MOSFET. Biassing (2)

Examples of Biassing circuits :

Fixed biasing

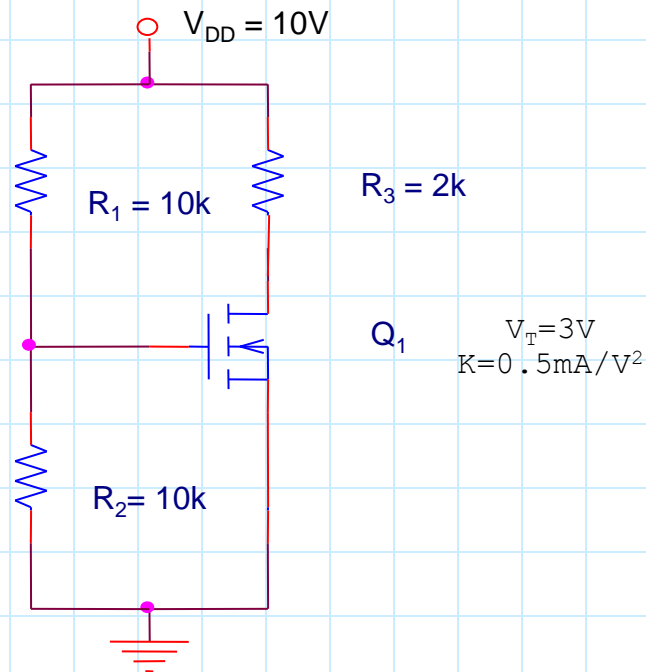


Drain feedback



# Enhancement MOSFET. Biassing (3)

Biassing with  
resistor divider



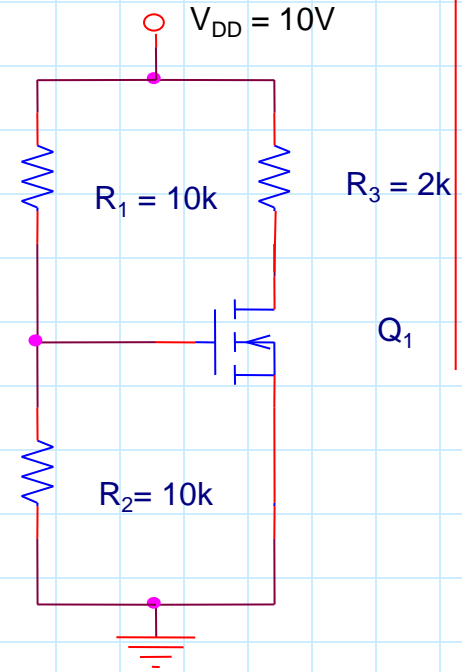
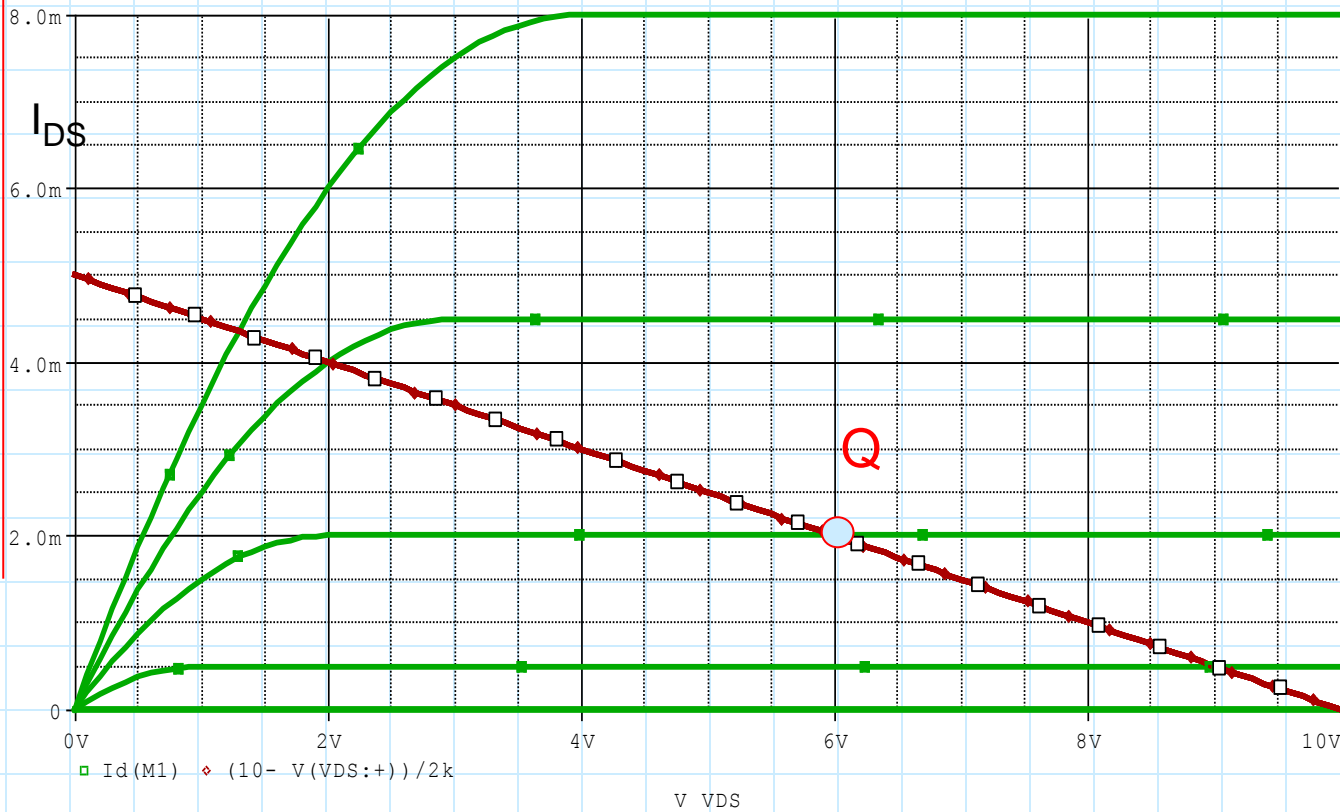
2 solutions for  $I_{DS} \rightarrow$  you choose the one for which  $V_{GS} > V_T$



# The load line

Load line:  $V_{DS} = V_{DD} - I_{DS} \times R_D$

The **quiescent point (Q)** is determined by intersecting the characteristic curve of MOSFET and the load line.



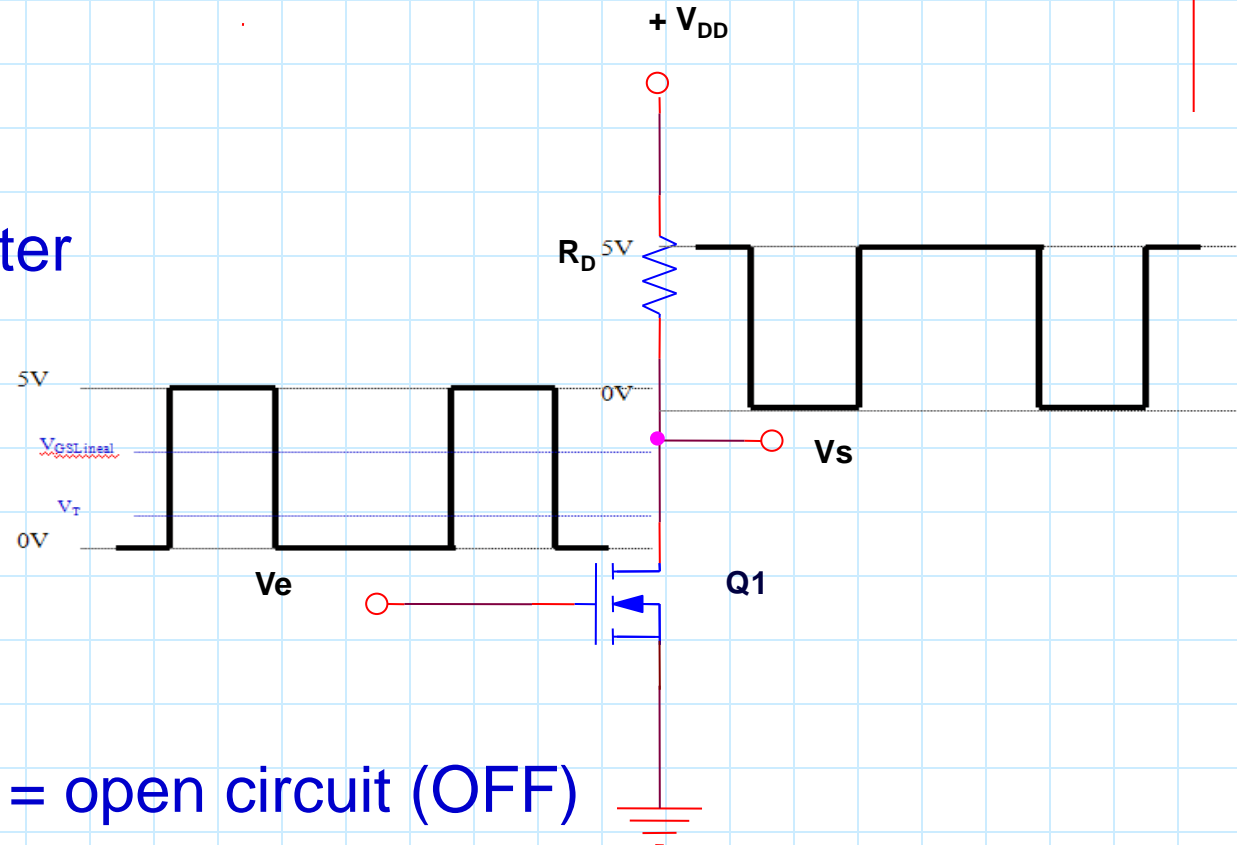
$$V_T = 3V$$

$$K = 0.5 \text{ mA/V}^2$$

## 2.3 The MOSFET in switching mode

- The transistor operates between cut-off and linear regions

NMOS inverter



$$V_e = V_{GS}$$

Two state:

$V_e < V_T \rightarrow \text{Mosfet} = \text{open circuit (OFF)}$

$V_e = V_{DD} \rightarrow \text{Mosfet} \approx R_{on}$  (very low resistance - ideally a closed switch-ON)

# The MOSFET in switching mode (2)

$$V_e = V_{GS}$$

Two state:

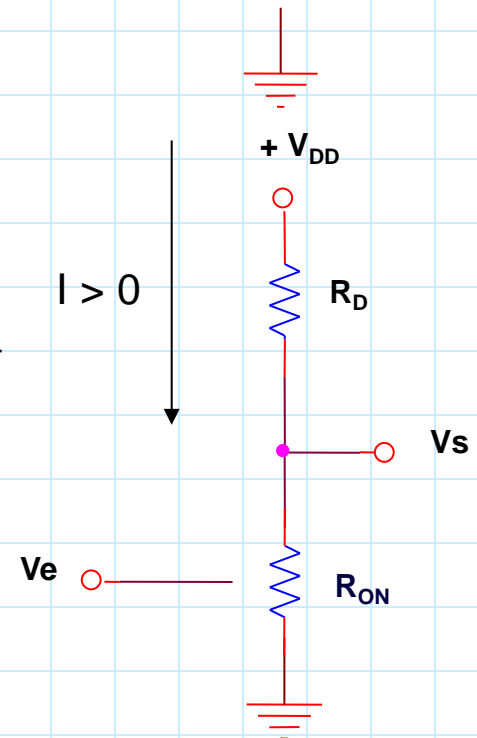
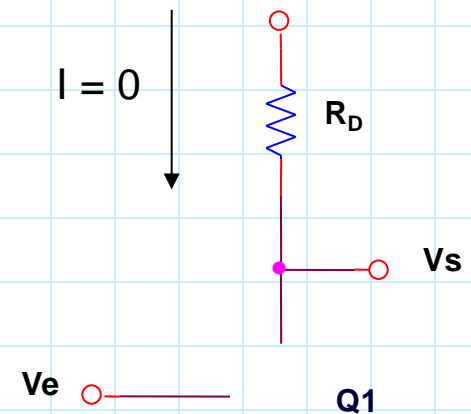
•  $V_e < V_T \rightarrow \text{Cut-off} \rightarrow V_{OH} = V_{DD} = "1"$

•  $V_e = V_{DD} \rightarrow \text{Mosfet} \approx R_{on}$

$$R_{ON} \approx \frac{1}{2 \cdot K(V_{GS} - V_T)} ; V_{OL} = V_{DD} \times \frac{R_{ON}}{R_D + R_{ON}}$$

if  $R_{on} \ll R_D \rightarrow V_{OL} \approx 0V = "0"$

There is static power consumption ( $I > 0$ )



# The MOSFET in switching mode (3)

NMOS inverter:

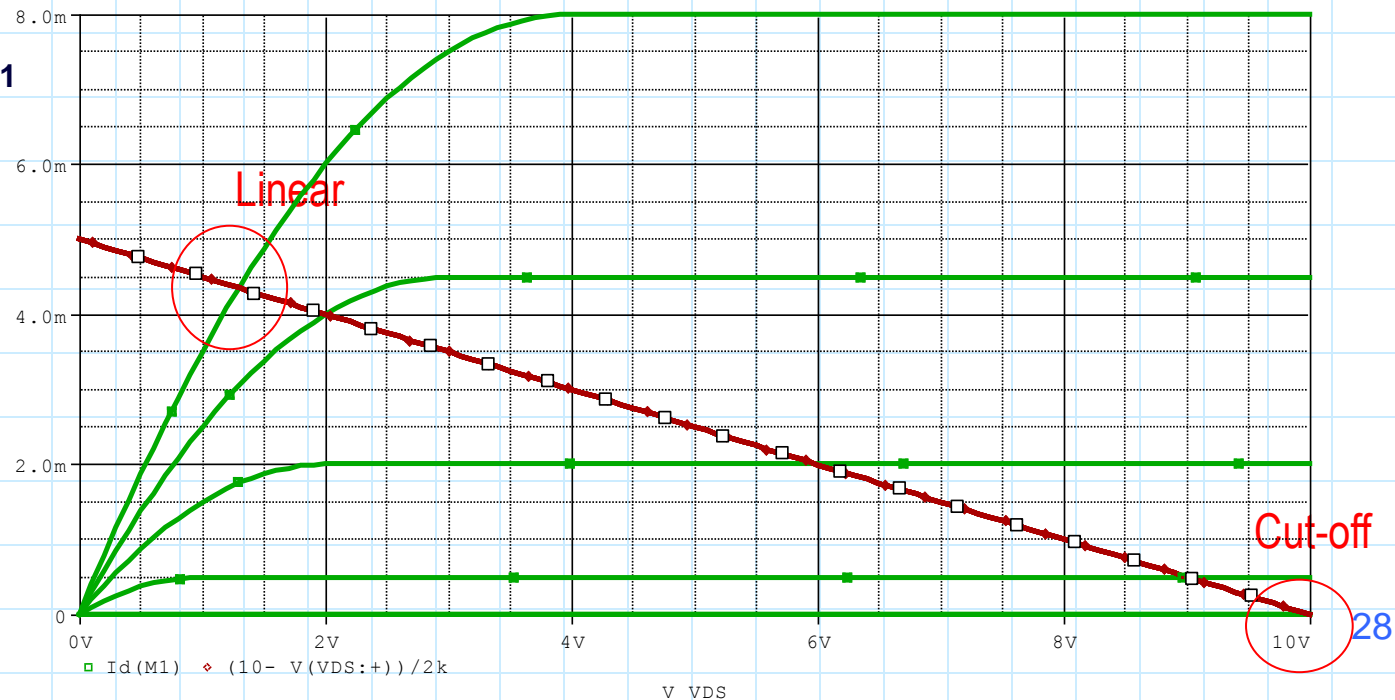
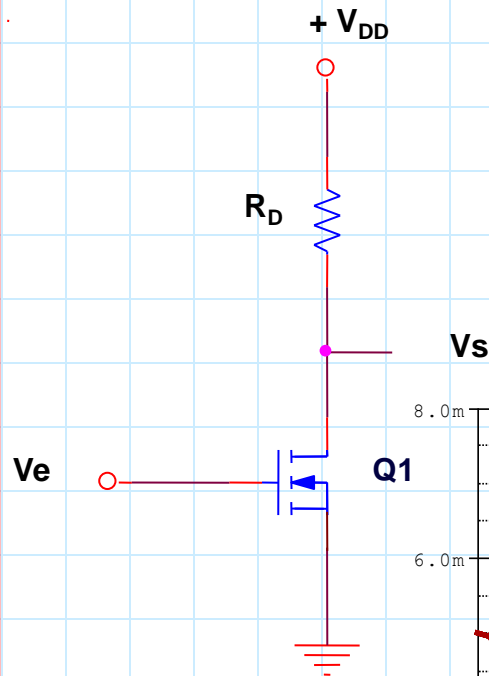
Load line= Loop D-S equation

$$V_{DD} = I_D R_D + V_{DS}$$

Intersection points:

Vertical axis  $\rightarrow I_D = V_{DD}/R_D$

Horizontal axis  $\rightarrow V_{DS} = V_{DD}$



# The MOSFET in switching mode (4)

## Example:

Design an NMOS inverter with pull-up resistor

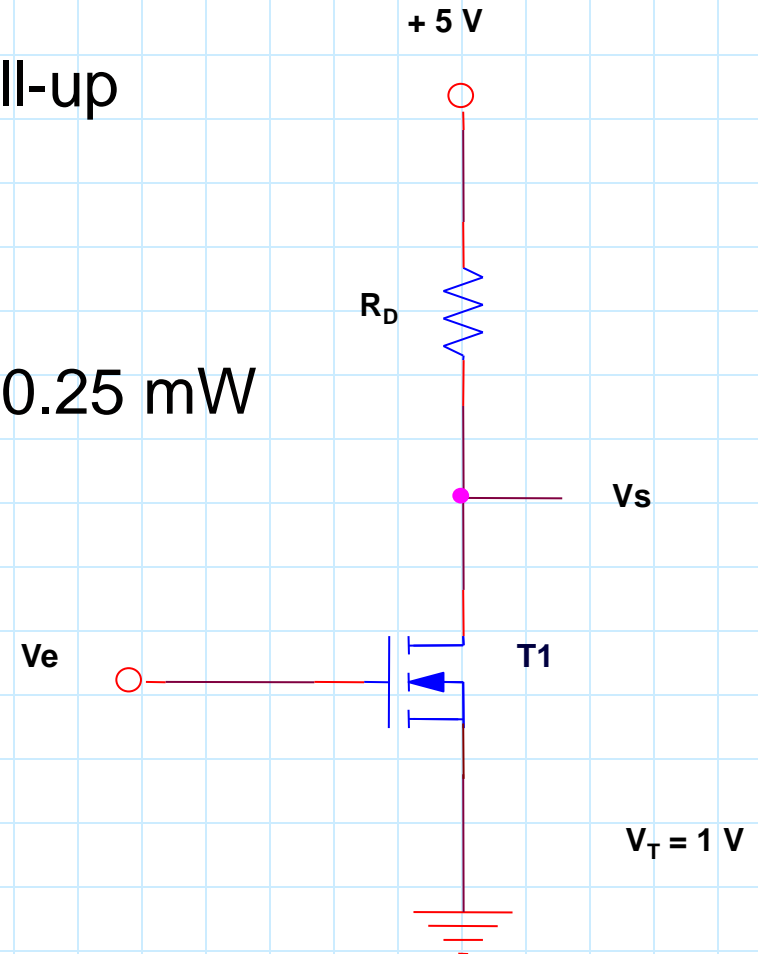
## Data:

Power consumption at low level = 0.25 mW

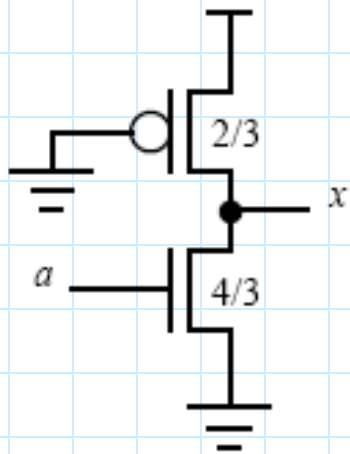
$$V_{OL} = 0.5V, V_{OH} = V_{DD} = 5V$$

Transistor:  $V_T = 1V$

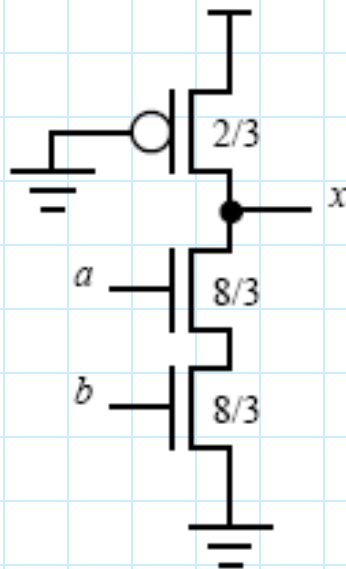
Find out  $R_{on}$  and  $K$



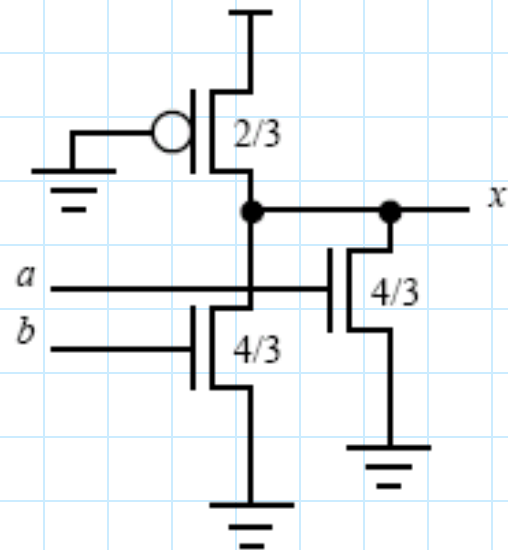
# Active loads. Pseudo-NMOS Logic



Inverter



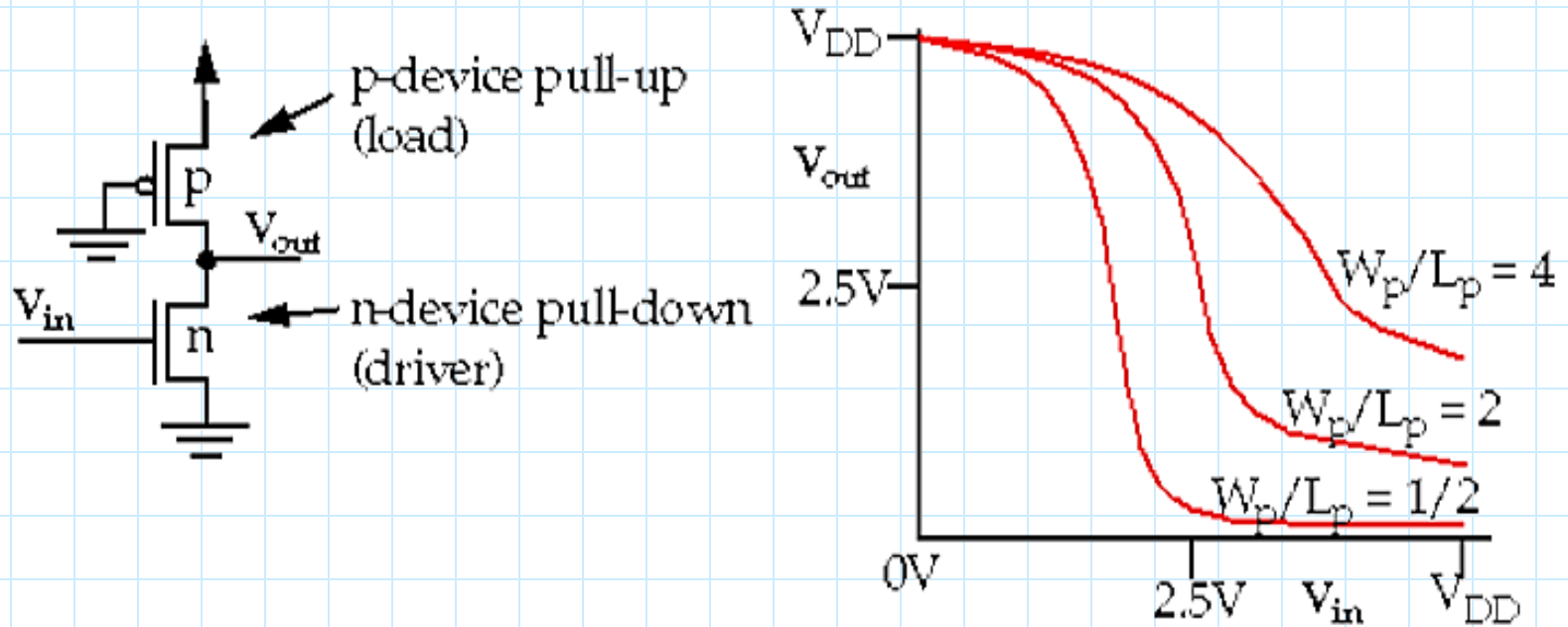
NAND



NOR

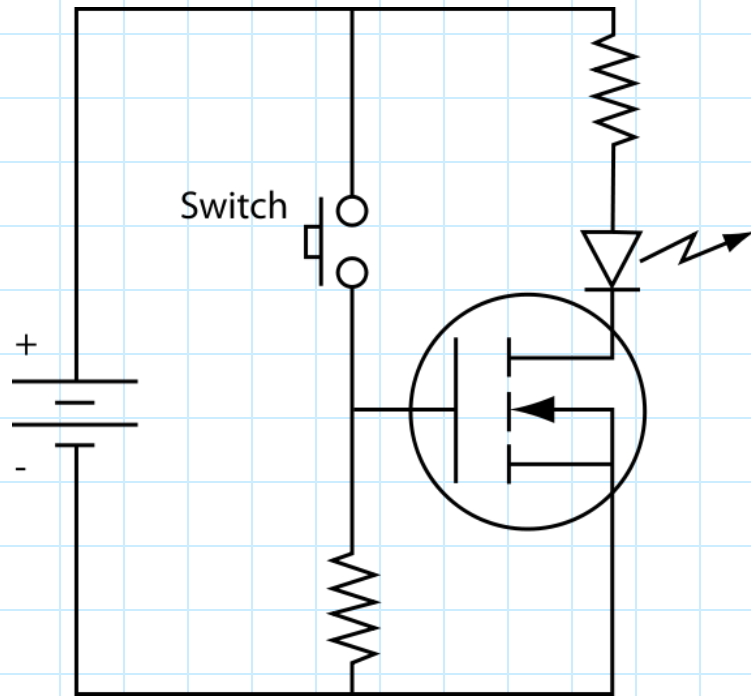
- PMOS transistor always conducting
- Saving Silicon area (no Rpull-up necessary)
- Used in ROM, PLA and FLASH

# Active loads. Pseudo-NMOS Logic



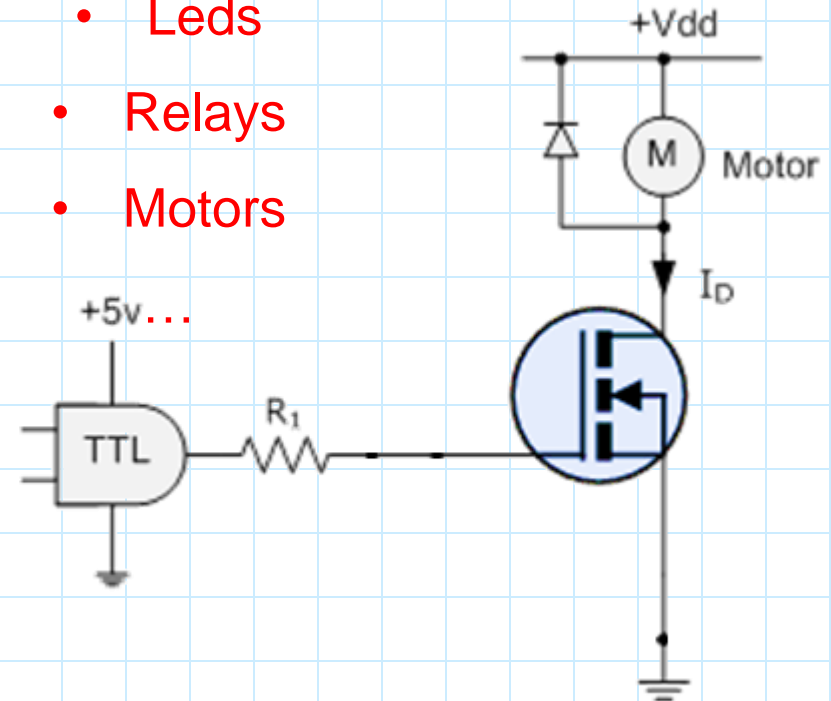
Transference curve versus  
channel size ( $W/L$ )

# The MOSFET in switching mode. Applications



We can control:

- Leds
- Relays
- Motors

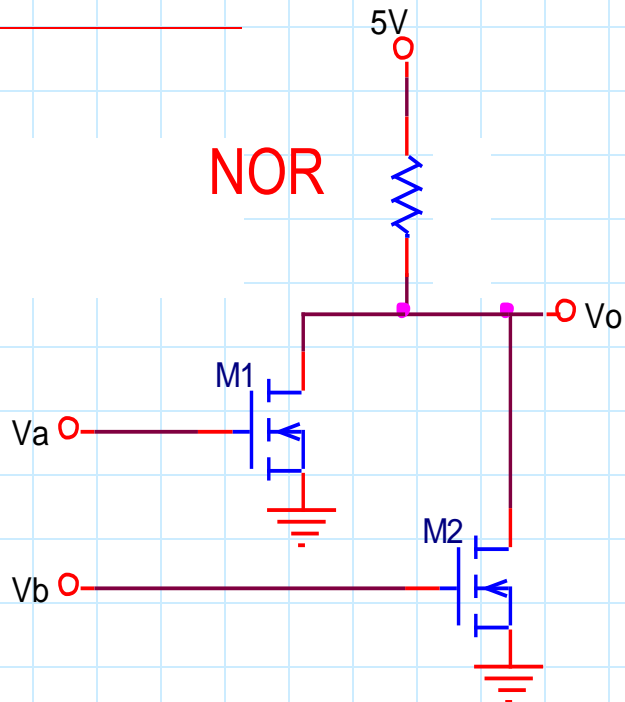


Switch pushed  $\rightarrow V_{GS} = V_{DD} \rightarrow$  Mosfet On (closed switch)  $\rightarrow$  LED ON

Switch released  $\rightarrow V_{GS} = 0 \rightarrow$  Mosfet off (open switch)  $\rightarrow$  LED OFF



# 2.4 NMOS logic gates



Let's assume:

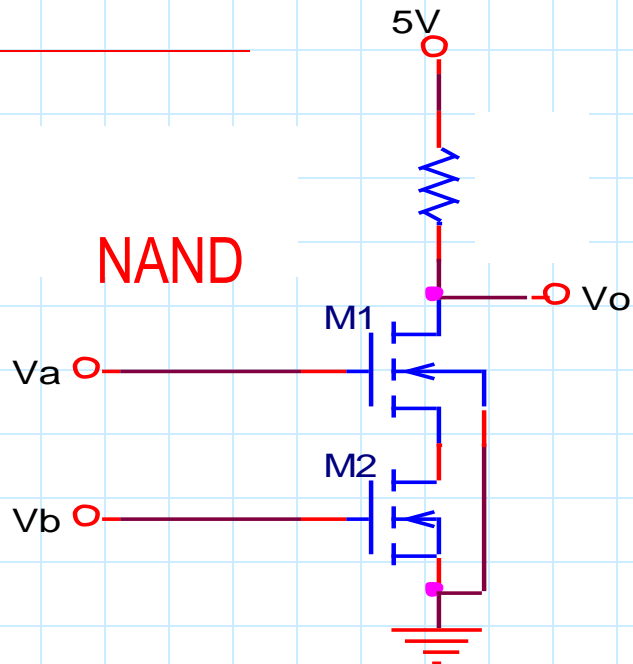
"0" = 0V

"1" = 5V

Transistors in parallel

Va	Vb	M1(OFF/ON)	M2 (OFF/ON)	Vo
0	0			
0	1			
1	0			
1	1			

# 2.4 NMOS logic gates



Let's assume:

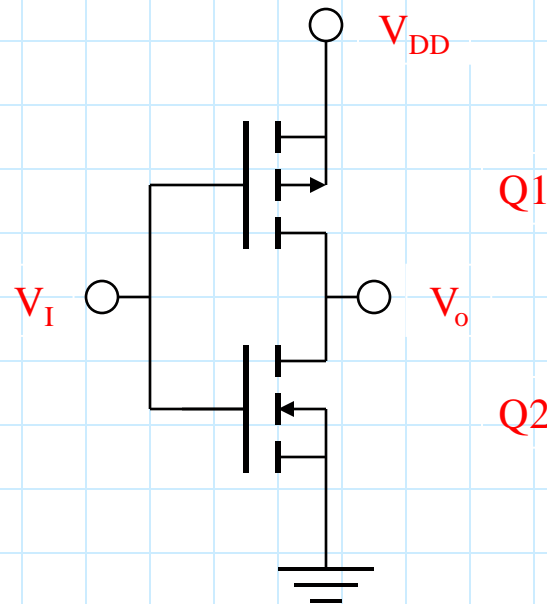
"0" = 0V

"1" = 5V

Transistors in  
series

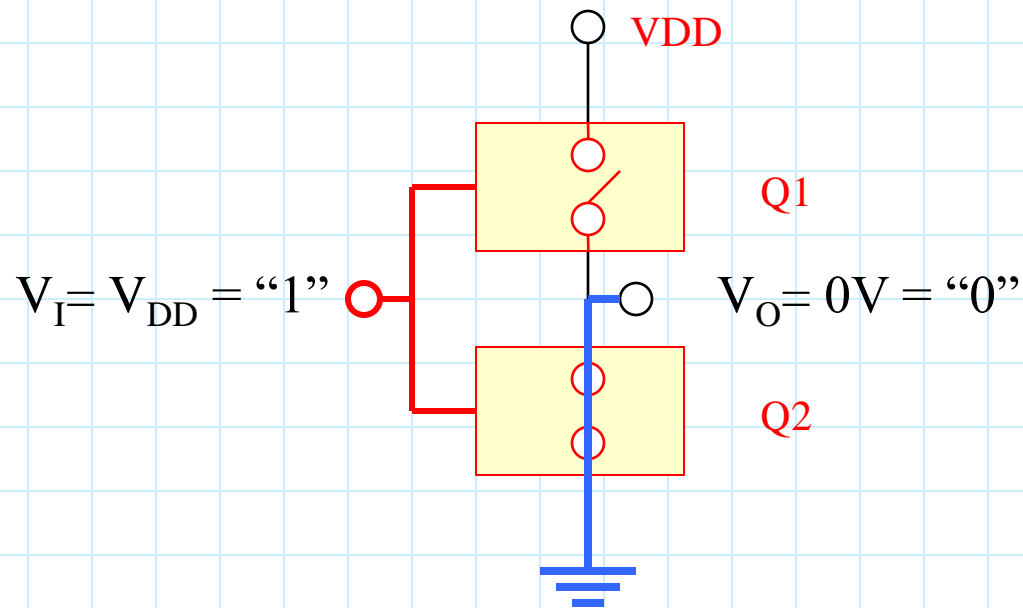
$V_a$	$V_b$	M1(OFF/ON)	M2 (OFF/ON)	$V_o$
0	0			
0	1			
1	0			
1	1			

## 2.5. The CMOS inverter



Digital input:  $V_I = 0V = \text{"0"};$      $V_I = V_{DD} = \text{"1"}$

## 2.5. The CMOS inverter (2)

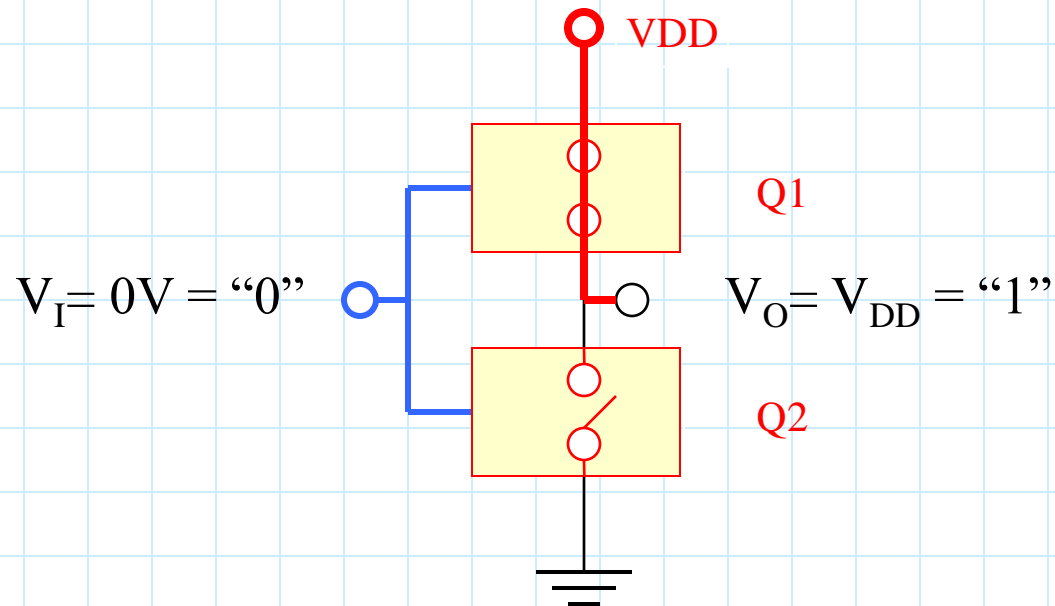


$$V_{GS1} = V_{DD} - V_{DD} = 0V > -V_T \Rightarrow \text{PMOS cut-off}$$

$$V_{GS2} = V_{DD} - 0V = V_{DD} > V_T \Rightarrow \text{NMOS conducts}$$

The static consumption is = 0

## 2.5. The CMOS inverter (3)

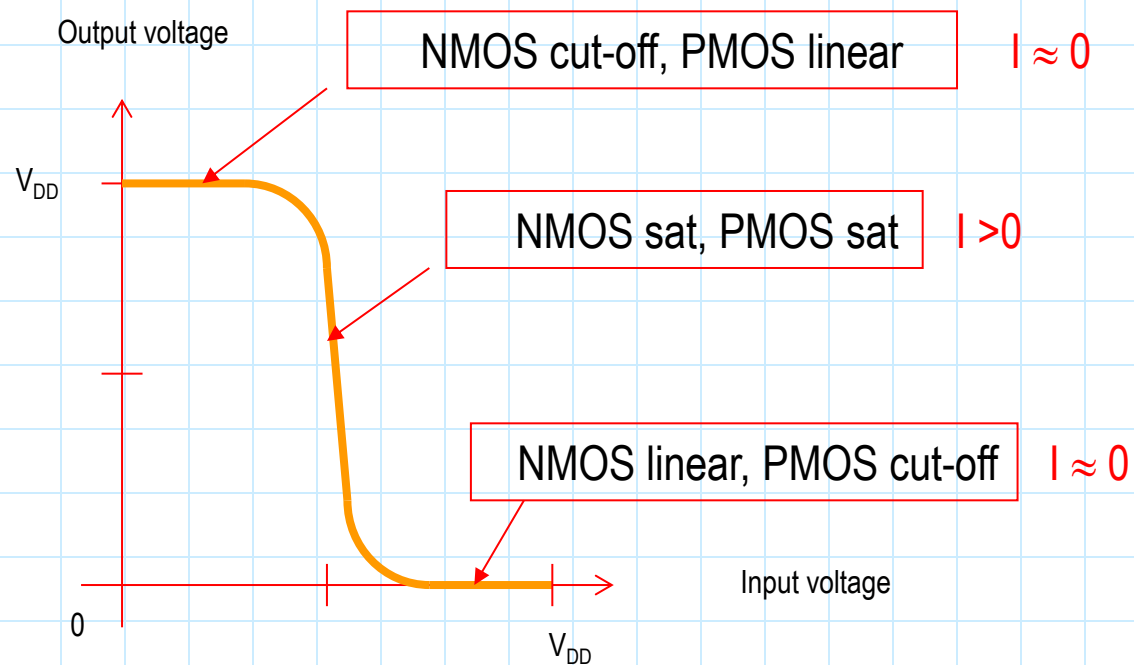


$$V_{GS1} = 0V - V_{DD} = -V_{DD} < -V_T \Rightarrow \text{PMOS conducts}$$
$$V_{GS2} = 0V - 0V = 0V < V_T \Rightarrow \text{NMOS cut-off}$$

The static consumption is = 0

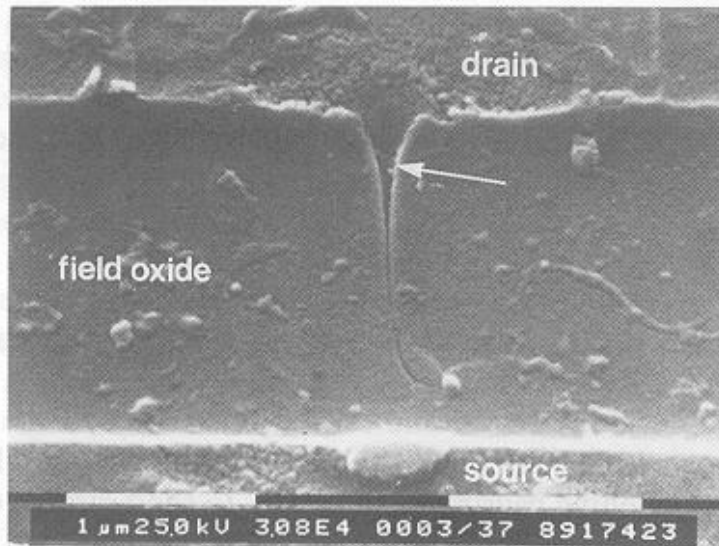
## 2.5. The CMOS inverter (4)

Transference curve:



## 2.6. Protection of MOSFET transistors (1)

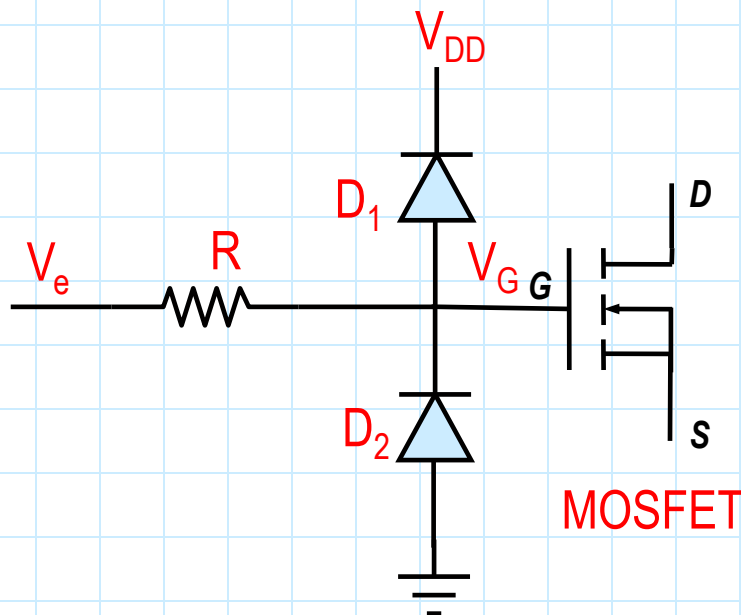
- MOSFET are sensitive to:
  - Overvoltages
  - Overcurrents
  - High electrostatic potentials
  - Radiations
- *thin*ox layer: very thin,  $< 40\text{\AA}$  in VLSI ( $1\text{\AA} = 0.1\text{ nm}$ )



Thin oxide layer breakdown caused by electrostatic potentials at the gate

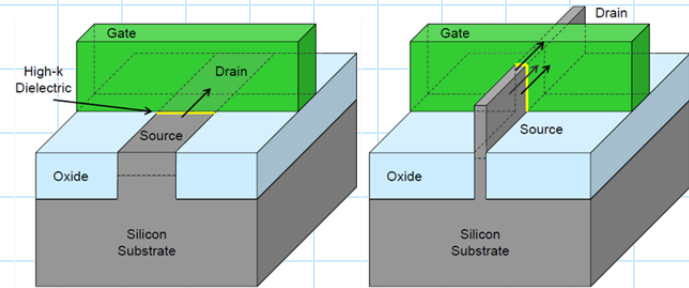
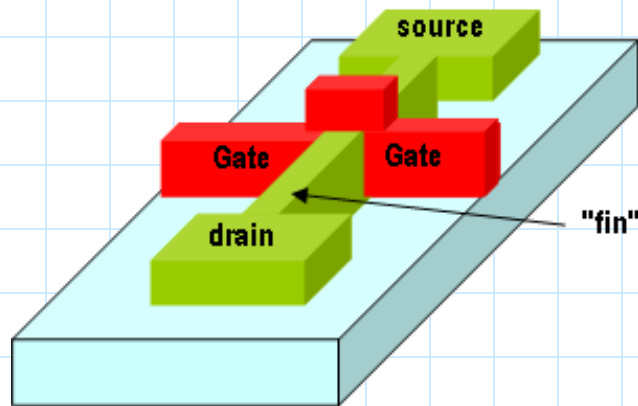
## 2.6. Protection of MOSFET transistors (2)

- Precautions when handling MOSFETs :
  - \* Storage in conducting material
  - \* Careful human manipulation
  - \* In operation, connect unused inputs to ground or to  $V_{DD}$ .
- Clamping circuits





# Latest developments : FinFET, tri-gate



Traditional

3D FinFET

- Higher speed
- Less consumption
- New material for isolators and semiconductors
  - Isolators:  $\text{HfO}_2$ ,  $\text{ZrO}_2$ ,  $\text{Si}_3\text{N}_4$
  - More mobility in channel, using different materials than Si: InGaAS, ....

# 2.7 Summary

- We have introduced the features that have made the MOSFET transistor the most important device of the digital age. We have assessed the importance and applications of this transistor.
- We have studied the internal functioning of enhancement MOSFETs, their structure, equations, curves and operating regions .
- We have learn how to solve DC circuits based on one or more MOSFET transistors.
- We know the switching mode of the MOSFETs, the states and the conditions of the transistor in this mode.
- We have introduced the main logic gates based on MOSFETs
- We have studied the basic techniques to protect these devices.